



**FOR IMMEDIATE RELEASE**

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**SHENMAO to Exhibit Low-Temperature Solder Pastes at ECTC**

**SAN JOSE, CA — April 2019 —** SHENMAO America, Inc. is pleased to announce that it will exhibit at the 2019 IEEE Electronic Components and Technology Conference (ECTC), scheduled to take place May 28-31, 2019 at The Cosmopolitan of Las Vegas. The company will showcase its PQ10 series low temperature solder paste in Booth #500.

PQ10 series low temperature solder paste is made with the modified Sn/Bi alloy with lower melting point range from 137~142°C to 137~170°C. In comparison with SnAgCu, PQ10 offers reduced peak reflow temperature, energy consumption, and warpage of PCBs and components. In comparison with the Sn42/Bi58 Eutectic alloy, PQ10 series offers better ductility, finer microstructure, and increased drop and thermal reliability.



SHENMAO has successfully been approved by many international well-known electronic manufacturers. The company strives to offer the best quality without compromising cost and time-to-market while providing maximum value to all customers. SHENMAO America, Inc. blends SMT solder paste at its facility in San Jose, CA for distribution in North America.

For more information, please visit [www.shenmao.com](http://www.shenmao.com).

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**About SHENMAO**

SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.